PNZ334 (PN334)

Silicon planar type

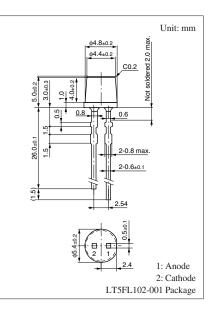
For optical control systems

Features

- Plastic type package (\$\$)
- High coupling capabillity suitable for plastic fiber
- High quantum efficiency
- High-speed response

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Reverse voltage | VR | 30 | V | |
| Power dissipation | P _D | 100 | mW | |
| Operating ambient temperature | T _{opr} | -25 to +85 | °C | |
| Storage temperature | T _{stg} | -30 to +100 | °C | |



Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

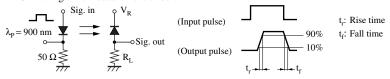
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--------------------------|----------------|---|-----|-----|------|------|
| Dark current | ID | $V_R = 10 V$ | | 0.1 | 10.0 | nA |
| Photocurrent *1 | IL | $V_R = 10 V, L = 1000 lx$ | 5 | 7 | | μΑ |
| Peak emission wavelength | λ_p | V _R = 10 V | | 850 | | nm |
| Rise time *2 | t _r | $V_{R} = 10 \text{ V}, R_{L} = 50 \Omega$ | | 2 | | ns |
| Fall time *2 | t _f | | | 2 | | ns |
| Terminal capacitance | Ct | $V_R = 0 V, f = 1 MHz$ | | 6 | | pF |
| Half-power angle | θ | The angle from which photocurrent | | 70 | | 0 |
| | | becomes 50% | | | | |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.

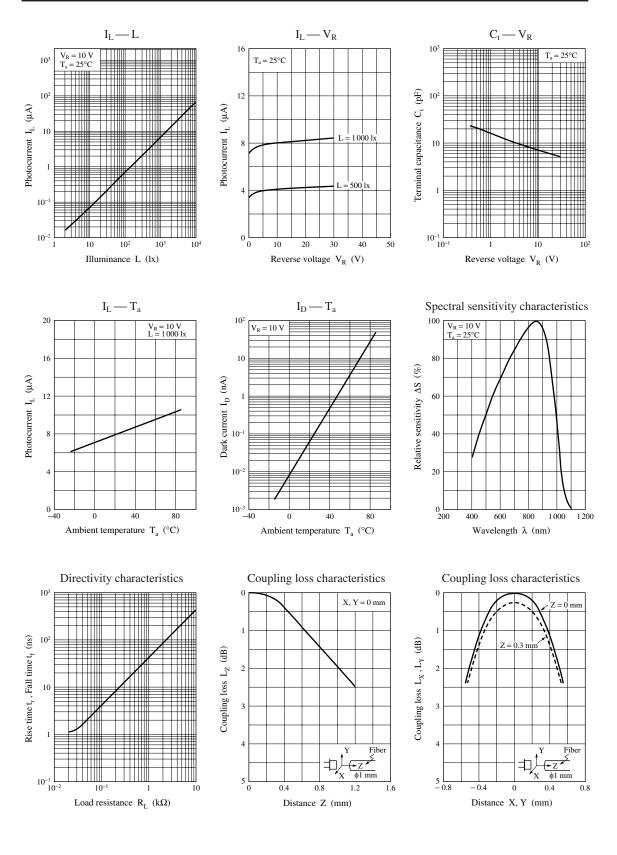
- 3. This device is designed be disregarded radiation.
- 4. *1: Source: Tungsten (color temperature 2856 K)

*2: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.

Panasonic



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